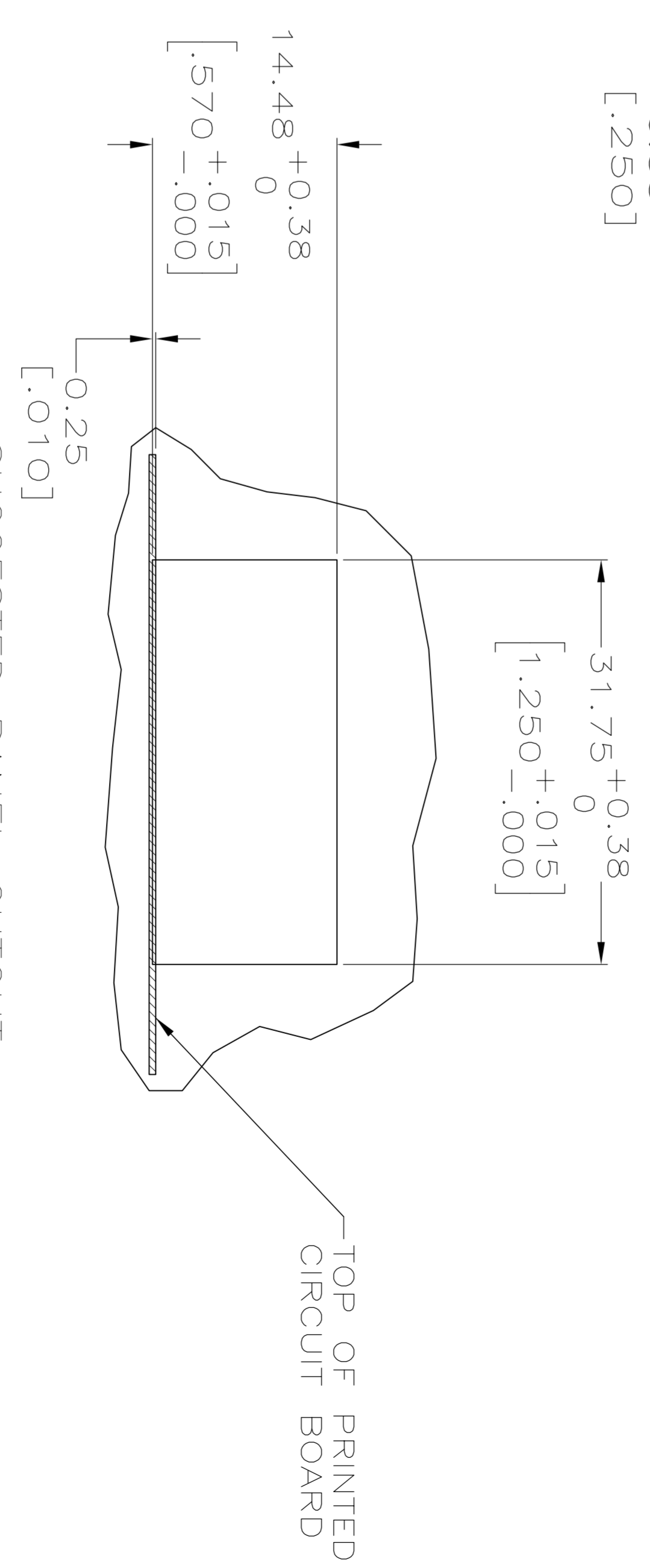


SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SCALE 2:1



SUGGESTED PANEL CUTOUT
 SCALE 2:1

1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, IR COMPATIBLE, UL 94V-0.

2 TERMINALS - 0.33 [0.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [0.000050] THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [0.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [0.000050] THICK NICKEL UNDERPLATE. SHIELD - 0.254 [0.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [0.000050] MINIMUM NICKEL AND 2.03 μm [0.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

3 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.

4 THIS HOLE REQUIRED FOR -2 ONLY.

5 REAR GROUND TAB NOT REQUIRED FOR -1.

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 16JUN2005		DWN. J. ALCORTA - DOCKS	
DIMENSIONS: mm[inches]		TOLERANCES, UNLESS OTHERWISE SPECIFIED:		CHK. WESTMAN 16JUN2005	
0 P/LC	±	0 P/LC	±	APPRO. FLICKINGER 16JUN2005	
1 P/LC	±	1 P/LC	±	NAME: Tyco Electronics Corporation	
2 P/LC	± 0.25 [0.01]	2 P/LC	± 0.25 [0.01]	Harrisburg, PA 17105-3608	
3 P/LC	± 0.15 [0.005]	3 P/LC	± 0.15 [0.005]	MODULAR JACK ASSEMBLY,	
FINISH		FINISH		2 PORT, 8 POSITION,	
MATERIAL		MATERIAL		RIGHT ANGLE, SHIELDED, CAT 4	
CUSTOMER DRAWING		CUSTOMER DRAWING		RESTRICTED TO	
WITH REAR PCB GROUND TAB		5406562-2		SCALE 4:1	
WITHOUT REAR PCB GROUND TAB		5406562-1		SHEET 1	
DESCRIPTION		PART NO.		REV. B	
DESCRIPTION		PART NO.		REV. B	

LOC	DIST	REV	DESCRIPTION	DATE	DWN	APP'D
AA	22	P	REV PER ECR-08-032447	18FEB2009	DZ	SY
B		U/R				